

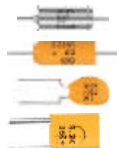


# KEMET Product Soldering Capability

## Surface Mount

Product Type		Soldering Capability	
		Peak Temp	Type
Ceramic MLCC Chip		260°C	Reflow
Tantalum MnO <sub>2</sub>		260°C	Reflow
KO-CAP Conductive Polymer, T520, T530		260°C*	Reflow
AO CAP Aluminum, A700		PWC = 605, 260°C PWC < 605, 250°C	Reflow
KO-CAP Conductive Polymer, T525		250°C	Reflow

## Through Hole

Product Type		Soldering Capability	
		Peak Temp	Type
Ceramic Conformally Coated Axials and Radials		260°C	Wave
Ceramic Commercial Molded Axials and Radials		260°C	Wave
Tantalum Through Hole		260°C	Wave

### \*Note

- T520, T530 V-case product 260°C capable since print week code (PWC) 501. All other T520, T530 sizes 260°C capable since PWC 524. Capability of product produced prior to these dates is 250°C. PWC format is YWW (Y = 1 digit year, WW = 2 digit week, for example, 533 = 33rd week of 2005) and is printed on the component face.